

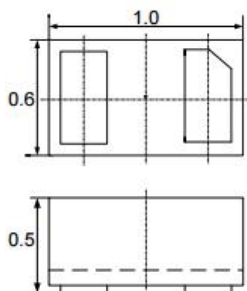
Description

The SEU0501P1 is designed with Salltech Punch-Through process TVS technology to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for use in high frequency designs such as USB 2.0 high speed, USB 3.0 super speed, VGA, DVI, HDMI, eSATA and other high speed line applications. It has been specifically designed to protect sensitive components which are connected to data and transmission lines from over voltage caused by ESD(electrostatic discharge), and EFT (electrical fast transients).

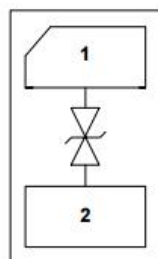
Features

- Ultra small package: 1.0x0.6x0.5mm
- Ultra low capacitance: 0.3pF typical
- No insertion loss to 3.0GHz
- Working voltage: 5V
- Low clamping voltage
- 2-pin leadless package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: ±15kV
Contact discharge: ±15kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)
- RoHS Compliant

Dimensions & Symbol (Unit: mm Max)



Package Dimensions



Circuit and Pin Schematic

Mechanical Characteristics

- Package: DFN1006-2 (1.0×0.6×0.5mm)
- Lead Finish: NiPdAu
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

Applications

- High Speed Line :USB1.0/2.0/3.0/3.1, VGA, DVI.SDI
- High Definition Multi-Media Interface(HDMI1.3/1.4/2.0)
- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Peripherals
- Cellular handsets and accessories
- Portable instrumentation

Marking Information



Details marking code reference specification of approval list

Ordering information

Part Number	Packaging	Reel Size
SEU0501P1	10000/Tape & Reel	7 inch

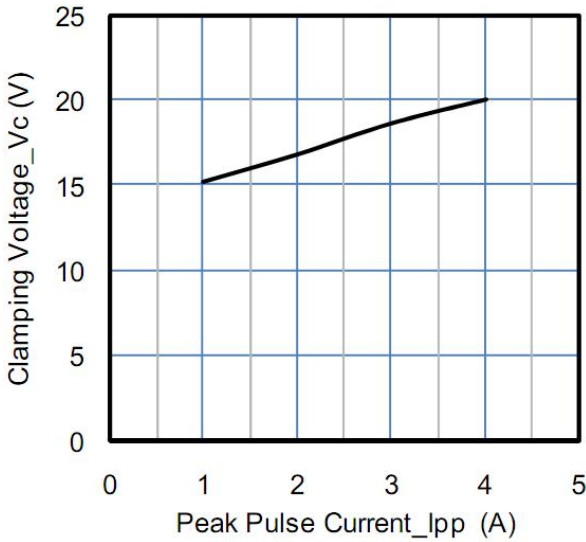
Absolute maximum ratings ($T_A=25^\circ\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p=8/20\mu\text{s}$ waveform)	P_{ppp}	80	W
ESD per IEC 61000-4-2 (Air)	VESD	± 15	kV
ESD per IEC 61000-4-2 (Contact)		± 15	
Operating Temperature Range	T_J	-55 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$

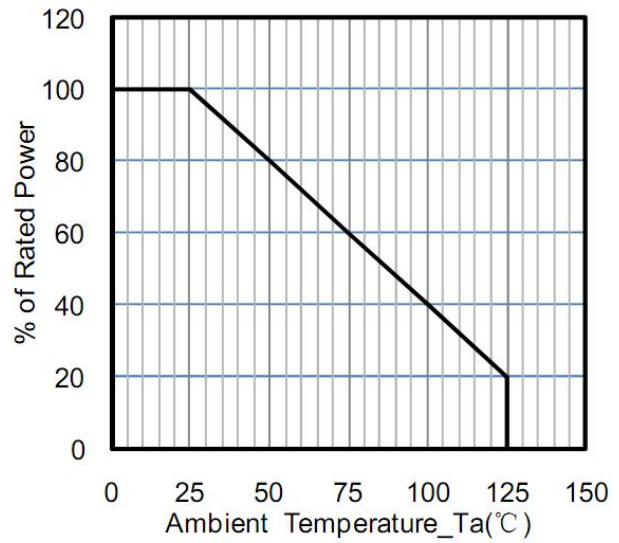
Electrical characteristics ($T_A=25^\circ\text{C}$)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V_{RWM}			5	V	
Breakdown Voltage	V_{BR}	6		10	V	$I_T = 1\text{mA}$
Reverse Leakage Current	I_R			1	μA	$V_{RWM} = 5.0\text{V}$
Clamping Voltage	V_C			12	V	$I_{PP} = 1\text{A}$ (8 x 20 μs pulse)
Clamping Voltage	V_C			20	V	$I_{PP} = 4\text{A}$ (8 x 20 μs pulse)
Junction Capacitance	C_J		0.3	0.5	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$

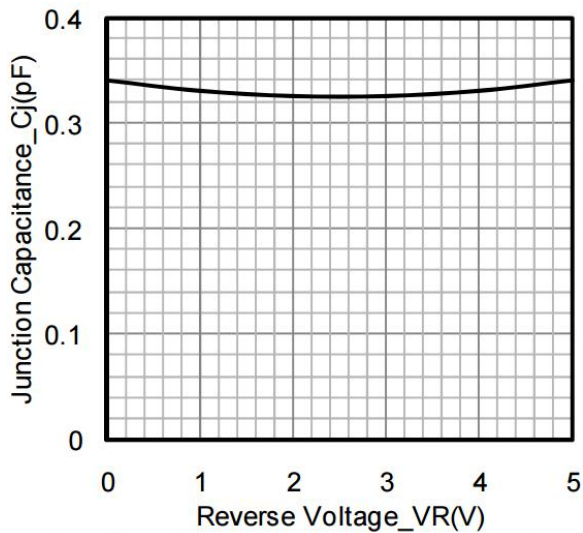
Typical Performance Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise Specified)



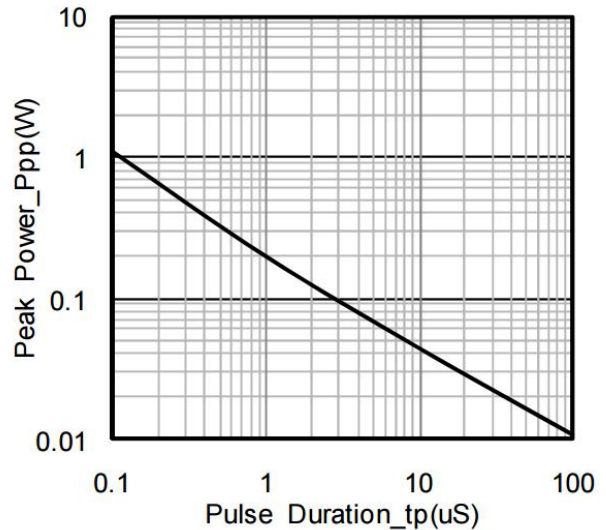
Clamping Voltage vs. Peak Pulse Current



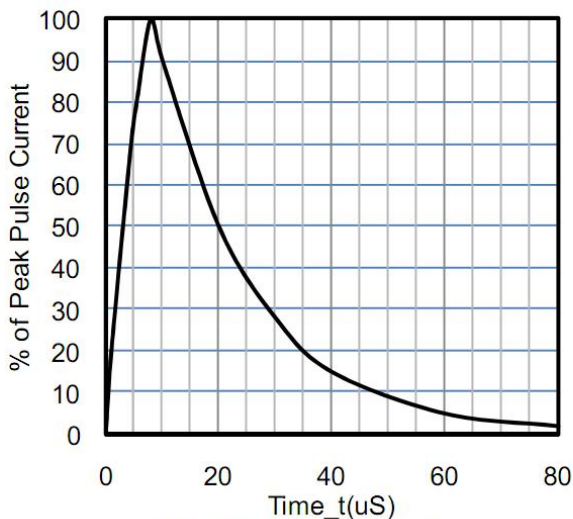
Power Derating Curve



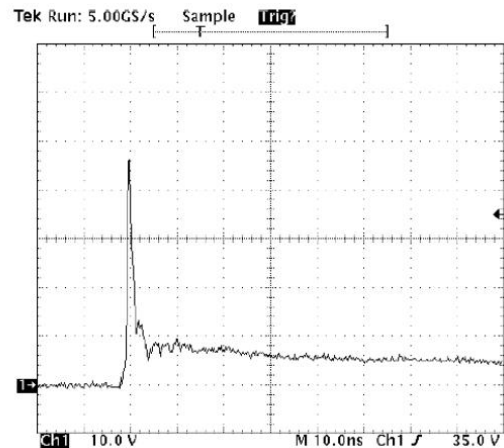
Junction Capacitance vs. Reverse Voltage



Peak Pulse Power vs. Pulse Time



8 X 20 μs Pulse Waveform

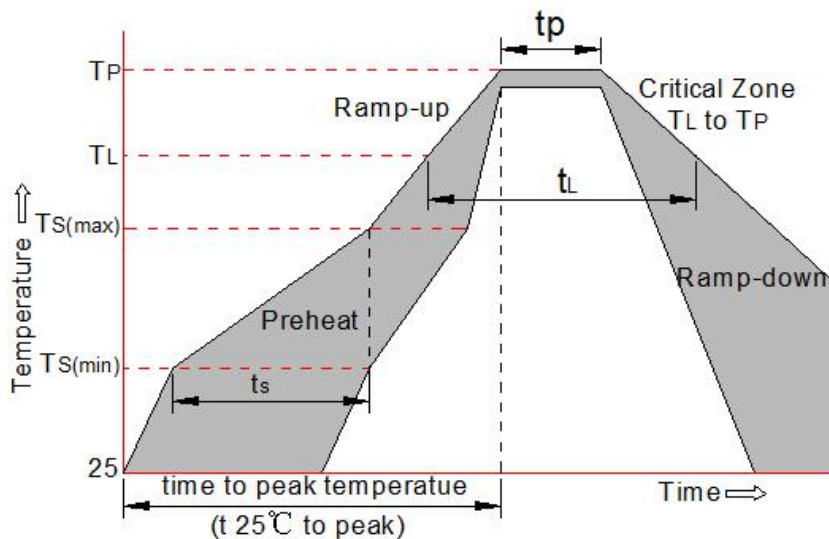


ESD Clamping Voltage

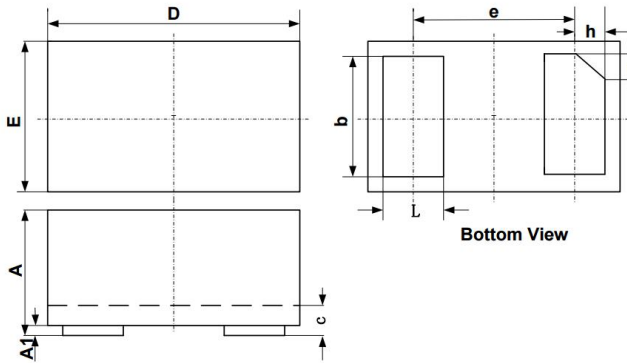
8 kV Contact per IEC61000-4-2

Soldering Parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

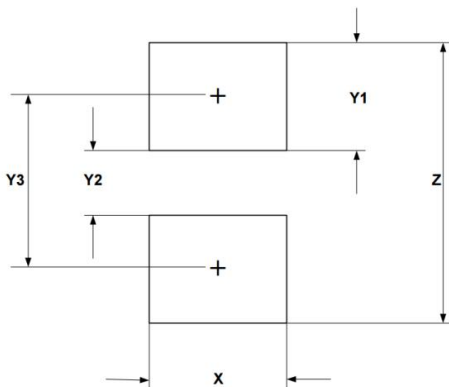


Package Mechanical Data



SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
c	0.12	0.15	0.18	0.005	0.006	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65 BSC			0.026 BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012
h	0.07	0.12	0.17	0.003	0.005	0.007

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
X	0.60	0.024
Y1	0.50	0.020
Y2	0.30	0.012
Y3	0.80	0.032
Z	1.30	0.052

Contact Information

SalltechMicroelectronics(shanghai)Co.,Ltd.

Area10.No.8.HuangduRoad.PudongDistrict.Shanghai.P.R.China.

TEL : +86-021-58131219

FAX : +86-021-58131183